Diodes Inc. Material Data Sheet
Rev: July 2009

SBR0220LP-p SBR0240LP-p SBR02M30LP-p SBR02U30LP-p SBR02U100LP-p SBR05U20LP-p

Part Number: **SBR DFN1006-2 Package** p = package designator
Weight (mg): 0.9202 See Data Sheet

Element	Material Group	Materials	CAS (if applicable)	Average mass homogeneous Materal(%)	Percent of whole (%)	Mass (mg)	ppm Homogeneous Material	ppm overall
Chip	Silicon w/Metal	Doped Silicon*	7440-21-3	100.00%	3.28	0.0302	1000000	32819
Leadframe	C7025	Cu	7440-50-8	95.90%	38.97	0.3586	959000	373720
		Si	7440-21-3	0.73%			7250	2825
		Ni	7440-02-0	3.20%			32000	12470
		Mg	7439-95-4	0.18%			1750	682
Leadframe Plating	Intenal plating	Ni	7440-02-0	100.00%	0.90	0.0083	1000000	9020
	middle plating	Pd	2023568	100.00%	0.09	0.0008	1000000	869
	outer plating	Au	7440-57-5	100.00%	0.01	0.0001	1000000	109
Bond Wire	Gold Wire	Gold	7440-57-5	100.00%	2.55	0.0235	1000000	25538
Encapsulation	EME-G770HT	Silica fused	60676-86-0	93.50%	52.50	0.4831	935000	490870
		Epoxy resin	------	3.00%			30000	15750
		Phenol resin	------	3.00%			30000	15750
		Carbon Black	1333-86-4	0.50%			5000	2625
Die Attach Epoxy	QMI519	Ag	7440-22-4	80.00%	1.70	0.0156	800000	13562
		palladium compound	----	0.15%			1500	25
		2,6-Di-tert-butyl-p-cresol	128-37-0	0.01%			50	1
		Hydroquinone	123-31-9	0.00%			1	0
		Acrylate	----	15.84%			158449	2686
		Bismaleimide resin	----	3.00%			30000	509
		Polymer of polybutadiene and anlydride	----	1.00%			10000	170
				Total	100.00	0.9202		1000000

Tolerance ±10%

This data is based on information provided by our suppliers. We believe it to be correct but do not routinely validate it by measurement. It is for guidance only and Diodes Inc. does not guarantee its absolute accuracy or completeness

***** The Silicon Chip is doped at atomic levels with trace amounts of elements that may include Phosphorus, Boron, Arsenic, and other elements. Metalization may include Titanium, Nickel, Aluminum, Silver or Gold These substances are not reported where their concentration is less than the minimum reportable level per the guidelines specified in the Tables of EIA JIG-101, *Material Composition Declaration for Electronic Products*.

This product or product family does not contain any of the following substances except as **CURRENTLY** exempted by ELV II and RoHS and reported above:

Asbestos
Antimony Compounds
Azo compounds
Cadmium and cadmium compounds
Certain Shortchain Chlorinated Paraffins
Chlorinated organic compounds
Dimethyl fumarate
Halogens
Hexavalent chromium compounds
Lead and lead compounds
Mercury and mercury compounds
Organic tin compounds
Ozone Depleting Substances - Class I (CFCs, HBFCs, etc.)
Ozone Depleting Substances - Class II (HCFCs)
Perfluorooctane Sulphonate (PFOS) or related compounds
Polybrominated biphenyls (PBB) and Polybrominated diphenyl ethers (PBDE) including DecaBDE
Polychlorinated Biphenyls (PCBs)
Polychlorinated Naphthalenes (> 3 chlorine atoms)
Radioactive Substances
Red Phosphorous
Tributyl Tin (TBT) and Triphenyl Tin (TPT)
Tributyl Tin Oxide (TBTO)

REACH SVHCs and other Substances of Concern:

Anthracene
4,4'- Diaminodiphenylmethane
Dibutyl phthalate
Cyclododecane
Cobalt dichloride
Diarsenic pentaoxide
Diarsenic trioxide
Sodium dichromate, dihydrate

Beryllium, Beryllium Alloys and Compounds
Hydrazine
Tetrachloroethylene
Toluene
Toluene Diisocyanate

5-tert-butyl-2,4,6-trinitro-m-xylene (musk xylene)
Bis (2-ethyl(hexyl)phthalate) (DEHP)
Hexabromocyclododecane (HBCDD)
Alkanes, C10-13, chloro (Short Chain Chlorinated Paraffins)
Bis(tributyltin)oxide
Lead hydrogen arsenate
Triethyl arsenate
Benzyl butyl phthalate

Methylene Chloride
Trichloroethene
Methyl Ethyl Ketone
Xylenes